

Title (en)
METHODS AND APPARATUS FOR ELECTRICAL, MECHANICAL AND/OR CHEMICAL REMOVAL OF CONDUCTIVE MATERIAL FROM A MICROELECTRONIC SUBSTRATE

Title (de)
METHODEN UND VORRICHTUNG ZUR ELEKTRISCH-, MECHANISCH- UND/ODER CHEMISCHEN ENTFERNUNG EINES LEITENDEN MATERIALS VON EINEM MIKROELEKTRONISCHEN SUBSTRAT

Title (fr)
PROCEDES ET DISPOSITIF POUR LE RETRAIT D'UN MATERIAU CONDUCTEUR D'UN SUBSTRAT MICRO-ELECTRONIQUE PAR VOIE ELECTRIQUE, MECANIQUE OU CHIMIQUE

Publication
EP 1399956 A2 20040324 (EN)

Application
EP 02744464 A 20020620

Priority
• US 0219495 W 20020620
• US 88808401 A 20010621
• US 88776701 A 20010621
• US 88800201 A 20010621

Abstract (en)
[origin: WO03001581A2] A method and apparatus for removing conductive material from a microelectronic substrate. In one embodiment, the method can include engaging a microelectronic substrate with a polishing surface of a polishing pad, electrically coupling a conductive material of the microelectronic substrate to a source of electrical potential, and oxidizing at least a portion of the conductive material by passing an electrical current through the conductive material from the source of electrical potential. For example, the method can include positioning first and second electrodes apart from a face surface of the microelectronic substrate, disposing an electrolytic fluid between the face surface and the electrodes with the electrodes in fluid communication with the electrolytic fluid, and moving at least one of the microelectronic and the polishing pad relative to the other.

IPC 1-7
H01L 21/321; **B24B 37/04**

IPC 8 full level
C25F 3/14 (2006.01); **B24B 37/04** (2012.01); **H01L 21/3063** (2006.01); **H01L 21/3205** (2006.01); **H01L 21/321** (2006.01); **H01L 21/3213** (2006.01); **H01L 21/76** (2006.01); **H01L 21/762** (2006.01)

CPC (source: EP KR)
B24B 37/046 (2013.01 - EP); **C25F 3/30** (2013.01 - EP); **C25F 5/00** (2013.01 - EP); **C25F 7/00** (2013.01 - EP); **H01L 21/3063** (2013.01 - KR); **H01L 21/32125** (2013.01 - EP)

Citation (search report)
See references of WO 03001581A2

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
WO 03001581 A2 20030103; **WO 03001581 A3 20031030**; AU 2002316303 A1 20030108; CN 100356523 C 20071219; CN 1516894 A 20040728; EP 1399956 A2 20040324; EP 1399957 A2 20040324; JP 2004531649 A 20041014; JP 2004531899 A 20041014; JP 4446271 B2 20100407; KR 100598477 B1 20060711; KR 100663662 B1 20070103; KR 20040010773 A 20040131; KR 20040021616 A 20040310; WO 03001582 A2 20030103; WO 03001582 A3 20031030

DOCDB simple family (application)
US 0219495 W 20020620; AU 2002316303 A 20020620; CN 02812238 A 20020620; EP 02744464 A 20020620; EP 02746596 A 20020620; JP 2003507878 A 20020620; JP 2003507879 A 20020620; KR 20037016756 A 20031222; KR 20037016758 A 20031222; US 0219496 W 20020620